



#### COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

## **Product Summary**

Device	BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>C</sub> = +25°C	
Q1 12V		$17m\Omega$ @ V <sub>GS</sub> = 4.5V	31.3A	
Qī	120	$25m\Omega$ @ V <sub>GS</sub> = 2.5V	25.8A	
Q2	-20V	$38m\Omega$ @ V <sub>GS</sub> = -4.5V		-20.9A
		$53m\Omega$ @ $V_{GS} = -2.5V$	-17.7A	

## **Description and Applications**

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Motor Control
- Power Management Functions
- DC-DC Converters

## **Features and Benefits**

- 100% Unclamped Inductive Switching, Test in Production— Ensures More Reliable and Robust End Application
- High Conversion Efficiency
- Low Rds(ON) Minimizes On State Losses
- Low Input Capacitance
- · Fast Switching Speed
- Wettable Flank for Improved Optical Inspection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMC1018UPDWQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

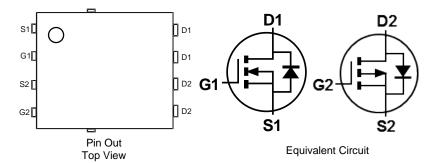
#### **Mechanical Data**

- Case: PowerDI<sup>®</sup>5060-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 (23)
- Weight: 0.097 grams (Approximate)

### PowerDI5060-8/SWP (Type UXD)







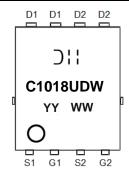
### Ordering Information (Note 4)

Part Number	Case	Packaging	
DMC1018UPDWQ-13	PowerDI5060-8/SWP (Type UXD)	2,500/Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

## **Marking Information**



⊃¦¦ = Manufacturer's Marking C1018UDW = Product Type Marking Code YYWW or YYWW = Date Code Marking YY or YY = Year (ex: 21 = 2021) WW = Week (01 to 53)



# **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Q1 Value	Q2 Value	Unit	
Drain-Source Voltage			12	-20	V
Gate-Source Voltage			±8	±12	V
Continuous Drain Current (Note 5) $ T_A = +25^{\circ}C $ $ T_A = +70^{\circ}C $		lD	10 8	-6.7 -5.4	А
Continuous Drain Current (Note 6)	T <sub>C</sub> = +25°C T <sub>C</sub> = +70°C	I <sub>D</sub>	31.3 25.0	-20.9 -16.7	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) (No	ote 6)	Ірм	125	-80	Α
Maximum Continuous Body Diode Forward Current (Not	Is	3.6	-3.2	А	
Pulsed Body Diode Forward Current (10µs Pulse, Duty 0	I <sub>SM</sub>	125	-83.6	А	
Avalanche Current, L = 0.1mH	las	24.1	-16.4	А	
Avalanche Energy, L = 0.1mH		Eas	29	13.5	mJ

## **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	PD	2.6	W
Thermal Resistance, Junction to Ambient (Note 5)		Reja	48.3	°C/W
Total Power Dissipation (Note 6)	P <sub>D</sub>	25	W	
Thermal Resistance, Junction to Case (Note 6)		Rejc	5.0	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

## Electrical Characteristics Q1 N-Channel (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	12	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 12V$ , $V_{GS} = 0V$	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.6	0.8	1.5	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance	Process	_	9.6	17	mΩ	Vgs = 4.5V, ID = 11.8A	
Static Drain-Source On-Resistance	RDS(ON)	_	11.2	25	mΩ	$V_{GS} = 2.5V, I_{D} = 9.8A$	
Diode Forward Voltage	VsD	_	0.7	1.2	V	Vgs = 0V, Is = 2.9A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss		1525	_	pF	., ., ., .,	
Output Capacitance	Coss	_	329	_	pF	V <sub>DS</sub> = 6V, V <sub>GS</sub> = 0V, f = 1MHz	
Reverse Transfer Capacitance	Crss	_	303	_	pF	1 - 11/11/12	
Gate Resistance	Rg	_	1.6	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	17.1	_	nC		
Total Gate Charge (Vgs = 8V)	Qg	_	30.4	_	nC	V <sub>DS</sub> = 6V, I <sub>D</sub> = 11.8A	
Gate-Source Charge	Qgs	_	2.6	_	nC	VDS = 6V, ID = 11.6A	
Gate-Drain Charge	Qgd	_	4.3	_	nC		
Turn-On Delay Time	t <sub>D</sub> (ON)	_	6.6	_	ns		
Turn-On Rise Time	t <sub>R</sub>	_	5.7	_	ns	$\begin{aligned} &V_{DD}=6V,\ R_L=6\Omega\ ,\\ &V_{GS}=4.5V,\ R_g=6\Omega,\ I_D=1A \end{aligned}$	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	41.5	_	ns		
Turn-Off Fall Time	tr	_	21.9	_	ns	]	
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	14.3	_	ns	IF = 11.8A, di/dt = 100A/µs	
Body Diode Reverse Recovery Charge	Q <sub>RR</sub>	_	2.3	_	nC	I <sub>F</sub> = 11.8A, di/dt = 100A/µs	

 Device mounted on FR-4 substrate PC board, 2oz. copper, with thermal bias to bottom layer 1inch square copper plate.
 Thermal resistance from junction to soldering point (on the exposed drain pad).
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing. Notes:

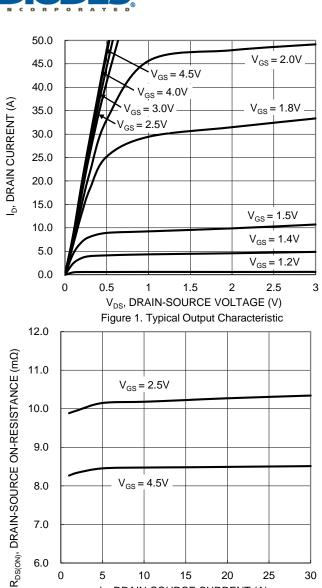


# Electrical Characteristics Q2 P-Channel (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current	IDSS	_	_	-1	μA	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V
Gate-Source Leakage	Igss	_	_	±100	nA	Vgs = ±12V, Vps = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	Vgs(th)	-0.6	-0.85	-1.5	V	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$
Static Drain-Source On-Resistance	RDS(ON)	_	30	38	mΩ	Vgs = -4.5V, ID = -8.9A
Static Drain-Source On-Nesistance	KDS(ON)	_	41	53	11152	$V_{GS} = -2.5V, I_{D} = -6.9A$
Diode Forward Voltage	VsD	_	-0.8	-1.2	V	Vgs = 0V, Is = -2.9A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	_	866	_		V <sub>DS</sub> = -6V, V <sub>GS</sub> = 0V, f = 1.0MHz
Output Capacitance	Coss	_	167	_	pF	
Reverse Transfer Capacitance	Crss	_	131	_		
Gate Resistance	Rg	_	4.9	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1.0MHz$
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Qg	_	8.6	_		
Total Gate Charge (V <sub>GS</sub> = -8V)	Qg	_	19	_	nC	01/1 004
Gate-Source Charge	Qgs	_	1.5	_	i iic	$V_{DS} = -6V, I_{D} = -8.9A$
Gate-Drain Charge	Qgd	_	2.5	_		
Turn-On Delay Time	td(ON)	_	5.8	_		
Turn-On Rise Time	t <sub>R</sub>	_	7.2	_		$V_{DD} = \text{-6V}, \ R_L = 6\Omega$ $V_{GS} = \text{-4.5V}, \ R_G = 6\Omega, \ I_D = \text{-1A}$
Turn-Off Delay Time	tD(OFF)	_	28.1	_	ns	
Turn-Off Fall Time	tF	_	14.6	_		
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	9.8	_	ns	I <sub>F</sub> = -8.9A, di/dt = -100A/μs
Body Diode Reverse Recovery Charge	Q <sub>RR</sub>	_	2.7	_	nC	I <sub>F</sub> = -8.9A, di/dt = -100A/μs

7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing. Notes:





 $V_{GS} = 4.5V$ 

10

8.0

7.0

6.0

I<sub>D</sub>, DRAIN-SOURCE CURRENT (A) Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

15

20

25

30

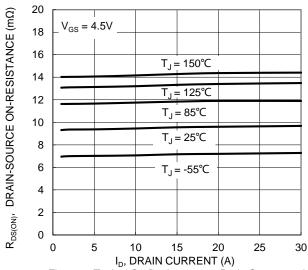


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

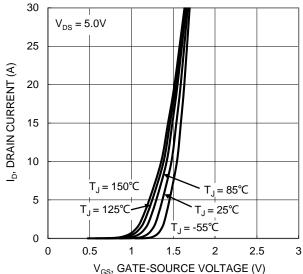
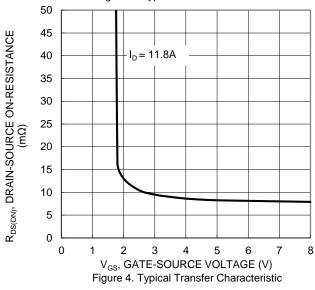


Figure 2. Typical Transfer Characteristic



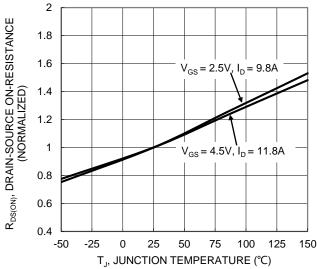


Figure 6. On-Resistance Variation with Junction Temperature





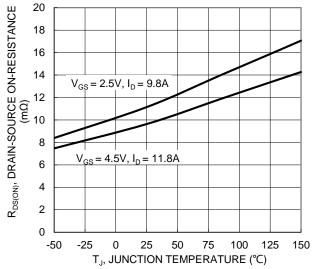


Figure 7. On-Resistance Variation with Junction Temperature

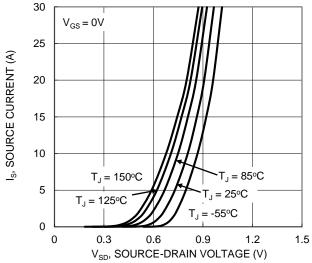
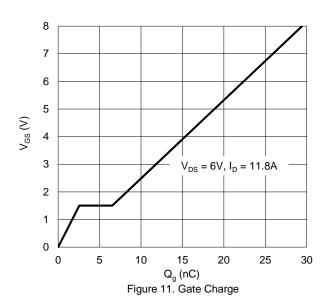


Figure 9. Diode Forward Voltage vs. Current



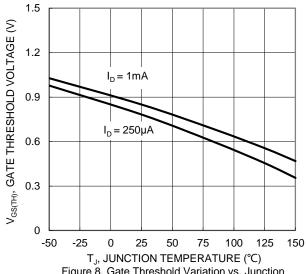
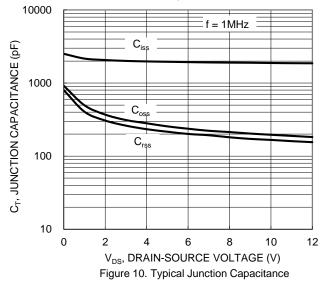
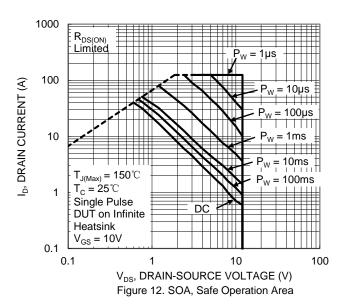


Figure 8. Gate Threshold Variation vs. Junction Temperature







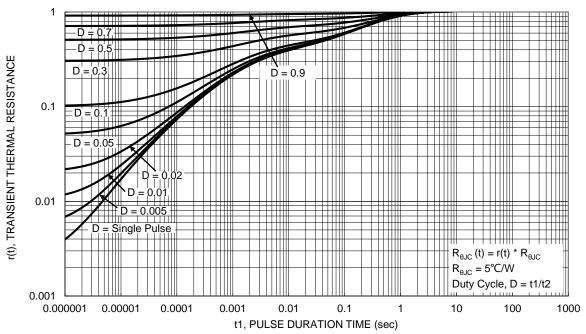
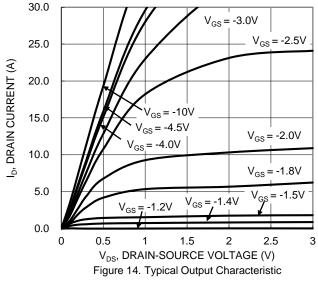


Figure 13. Transient Thermal Resistance





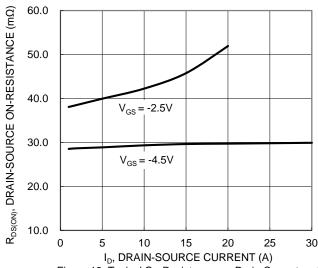


Figure 16. Typical On-Resistance vs. Drain Current and Gate Voltage

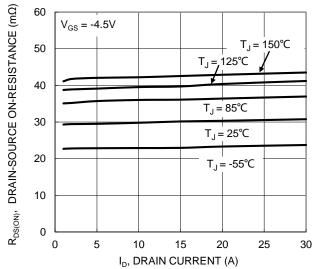
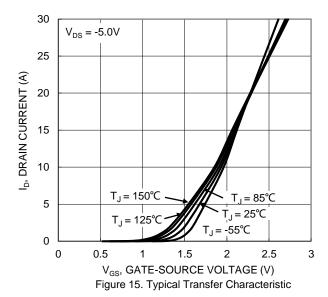
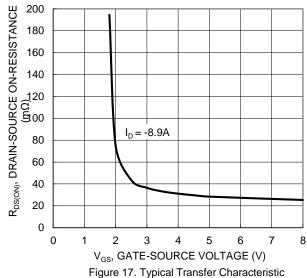


Figure 18. Typical On-Resistance vs. Drain Current and Temperature





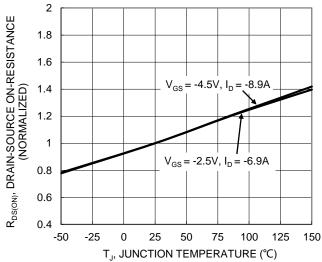


Figure 19. On-Resistance Variation with Junction Temperature





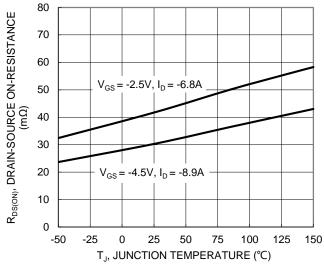
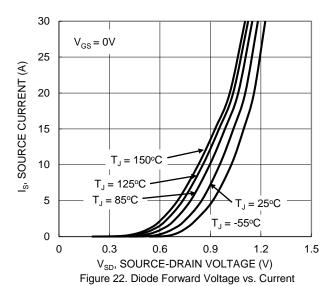
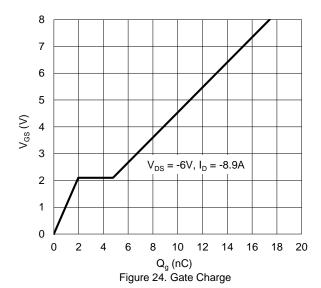


Figure 20. On-Resistance Variation with Temperature





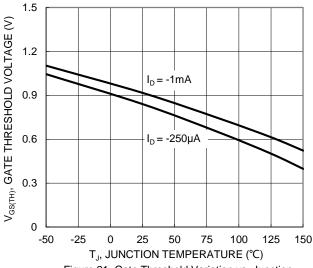
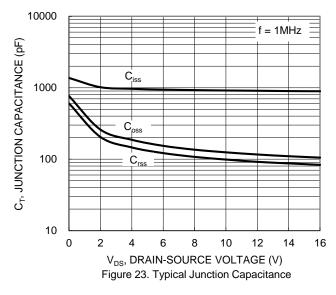
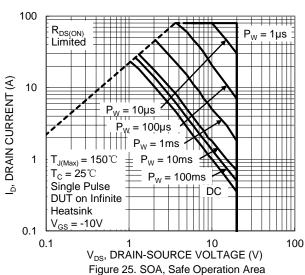


Figure 21. Gate Threshold Variation vs. Junction Temperature



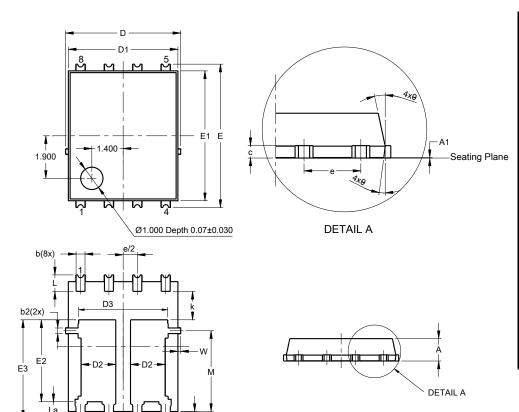




## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

## PowerDI5060-8/SWP (Type UXD)

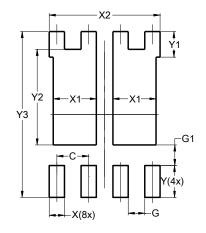


Po	PowerDI5060-8/SWP (Type UXD)							
Dim	Min	Max	Тур					
Α	0.90	1.10	1.00					
A1	0.00	0.05						
b	0.30	0.50	0.41					
b2	0.20	0.35	0.25					
b4	(	).25REF						
С	0.230	0.330	0.277					
D		.15 BS0						
D1	4.70	5.10	4.90					
D2	1.46	1.66	1.55					
D3	3.78	4.18	3.98					
Е	6.40 BSC							
E1	5.60	6.00	5.80					
E2	3.46	3.86	3.66					
E2a	4.195	4.595	4.395					
е	1	.27BS0						
k	1.05		-					
L	0.635	0.835	0.735					
La	0.635	0.835	0.735					
L1	0.200	0.400	0.300					
М	3.205	4.005	3.605					
W	0.025	0.225	0.125					
θ	10°	12°	11°					
θ1	6°	8°	7°					
All Dimensions in mm								

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

## PowerDI5060-8/SWP (Type UXD)



Dimensions	Value (in mm)
С	1.270
G	0.660
G1	0.820
Χ	0.610
X1	1.720
X2	4.420
Υ	1.270
Y1	1.020
Y2	3.810
Y3	6.610



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